



# M T B F

(EIAJ RCR-9102B)

Model	G2W-12
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No.	Parts	Q'ty of Device	Failure rate [ $10^{-6}/H$ ]	Reference
1	IC Linear	4	0.0960	
2	Transistors NPN/PNP	0	0.0000	
3	Transistors Power NPN/PNP	2	0.0840	
4	FET MOS FET	2	0.1980	
5	Diodes FR	4	0.0880	
6	Diodes Zener	2	0.0480	
7	Diodes bridge	4	0.2640	
8	Resistors Metal Film	32	0.5120	
9	Resistors Power Film	6	0.2460	
10	Resistors variable	2	0.0320	
11	Capacitors Aluminum Electrolytic	12	0.2280	
12	Capacitors Film	8	0.0672	
13	Transformer Power	1	0.3600	
14	Fuses	3	0.0600	
15	Connectors Printed Circuit Board	6	0.3120	
16	Connection Hand Solder	19	0.0494	
17	Connection Flow Solder	283	0.1472	
18	Connection Crimp	22	0.0136	
19	Connection Screw	5	0.0050	
20	Printed Circuit Board Through Hole	2	0.0900	
Total Failure Rate [ $10^{-6}/H$ ]			2.9004	

M T B F	[H]	344,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-